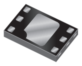
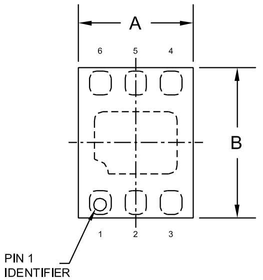
Package Details
TLM621H Case

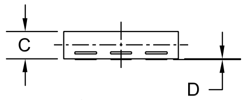

Top View


Bottom View

Mechanical Drawing



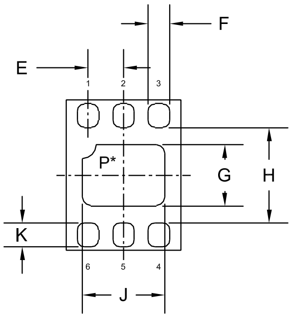
TOP VIEW



SIDE VIEW

DIMENSIONS				
	INCHES		MILLIMETERS	
SYMBOL	MIN	MAX	MIN	MAX
A	0.053	0.065	1.35	1.65
B	0.073	0.085	1.85	2.15
C	0.012	0.016	0.30	0.40
D	0.000	0.002	0.00	0.05
E	0.020		0.50	
F	0.008	0.012	0.20	0.30
G	0.027	0.035	0.69	0.89
H	0.053	0.057	1.35	1.45
J	0.039	0.047	0.99	1.19
K	0.011	0.015	0.28	0.38

TLM621H (REV:R0)



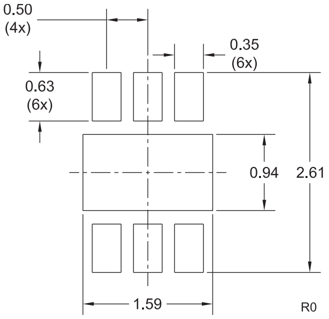
BOTTOM VIEW R0

* Exposed pad P internally connected to pins 3 and 4

Part Marking:
2-3 Character Alpha/Numeric Code

Lead Code:
Reference individual device data sheet.

Mounting Pad Geometry (Dimensions in mm)



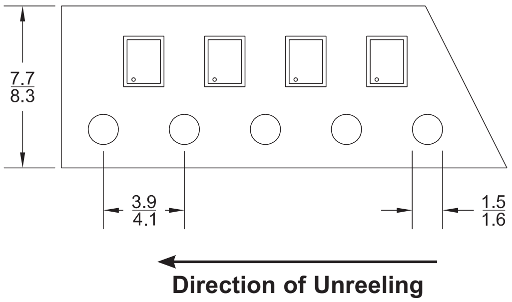
R1 (4-March 2010)

Package Details

TLM621H Case

Tape Dimensions and Orientation (Dimensions in mm)

Tape Width: 8mm



Devices are taped in accordance with Electronic Industries Association Standard EIA-481-1-A

Packaging Base

7” Reel = 3,000 pcs.

Reel Labeling Information

Each reel is labeled with the following information:
Central Part Number, Customer Part Number, Purchase Order Number, Quantity, Lot Number, Date Code, Ship Date and Marking Code.

Reel Packing Information

Reel Size	Reels per Box (Maximum)	Parts per Box (Maximum)	Box Dimensions		Shipping Weight (Max.)	
			INCH	CM	LB	KG
7”	9	27,000	9x9x5	23x23x13	3	2
	18	54,000	9x9x9	23x23x23	6	3
	40	120,000	21x9x9	53x23x23	13	6
	108	324,000	27x9x17	69x23x43	34	16

Ordering Information

- For devices taped and reeled on 7” reels, add TR suffix to part number.
- All SMDs are available in small quantities for prototype and manual placement applications.

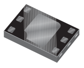
R1 (4-March 2010)

Material Composition Specification

TLM621H Case

Central Semiconductor Corp.

Top View



Bottom View

Device average mass . . . . **3.77 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	6.63%	0.25	Si	7440-21-3	6.63%	0.25	66,278
bond wire	gold	0.53%	0.02	Au	7440-57-5	0.53%	0.02	5,302
leadframe	Cu alloy	43.21%	1.63	Cu	7440-50-8	41.89%	1.58	418,876
				Ni	7440-02-0	1.01%	0.038	10,074
				Si	7440-21-3	0.27%	0.01	2,651
				Mg	7439-95-4	0.05%	0.002	530
die attach	silver epoxy	2.65%	0.1	Ag	7440-22-4	1.86%	0.07	18,558
				epoxy resin	Proprietary	0.8%	0.03	7,953
encapsulation*	EMC GREEN	46.39%	1.75	silica (fused)	60676-86-0	43.48%	1.64	434,783
				epoxy resin	29690-82-2	1.33%	0.05	13,256
				phenol resin	9003-35-4	1.33%	0.05	13,256
				carbon black	1333-86-4	0.27%	0.01	2,651
plating	Ni/Pd/Au Process	0.58%	0.022	Ni	7440-02-0	0.5%	0.019	5,037
				Pd	7440-05-3	0.05%	0.002	530
				Au	7440-57-5	0.03%	0.001	265

*EMC GREEN molding compound is Halogen-Free.

Disclaimer

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.